

IN THE CLAIMS

Please amend the claims as follows.

1-28. (Canceled)

29. (Original) A method of controlling a semiconductor parametric test system, comprising:
controlling via a control module concurrent operation of semiconductor test equipment
and operation of parametric test instrumentation.

30. (Original) The method of controlling a semiconductor parametric test system of claim
29, wherein the control module is implemented in software.

31. (Original) The method of controlling a semiconductor parametric test system of claim
29, wherein the control module is implemented in electronic hardware.

32. (Original) The method of controlling a semiconductor parametric test system of claim
29, wherein the semiconductor test equipment comprises at least one of a wafer loader, a wafer
positioner, a wafer chuck, a wafer tray loader, and a prober.

33. (Original) The method of controlling a semiconductor parametric test system of claim
29, wherein the parametric test instrumentation comprises at least one parametric test instrument
having at least one test probe or test receptacle.

34. (Original) The method of controlling a semiconductor parametric test system of claim
29, wherein operation of the parametric test instrumentation comprises operation of a test
equipment module, the test equipment module operable to facilitate control of the semiconductor
test equipment.

35. (Original) The method of controlling a semiconductor parametric test system of claim 29, wherein operation of the parametric test instrumentation comprises operating a parametric test instrumentation module, the parametric test instrumentation module operable to facilitate control of the parametric test instrumentation.

36. (Original) The method of controlling a semiconductor parametric test system of claim 29, wherein operation of the parametric test instrumentation comprises operating a semiconductor test parameter module.

37. (Original) The method of controlling a semiconductor parametric test system of claim 29, wherein the control module is further operable to concurrently manage test data.

38. (Original) The method of controlling a semiconductor parametric test system of claim 29, wherein the control module is further operable to provide fault-tolerant control of the test state via a state oscillator module, the state oscillator module operable to control the state of other system modules.

39. (Original) The method of controlling a semiconductor parametric test system of claim 38, wherein the state oscillator module changes the state of other system modules.

40. (Original) The method of controlling a semiconductor parametric test system of claim 38, wherein operation of the state oscillator module is controlled in synchronization with other system events by the control module.

41. (Original) The method of controlling a semiconductor parametric test system of claim 38, wherein the state oscillator module is operable to control module states within the system during operational superstates including an abort superstate, a pause superstate, and a lot run superstate; each superstate comprising an ordered sequence of states.

42. (Previously Presented) A method of controlling a semiconductor parametric test system, comprising:

controlling via a control module concurrent operation of semiconductor test equipment and operation of parametric test instrumentation;

controlling the state of at least one other system module via a state oscillator module, the state oscillator module controlled by the control module;

providing control of the semiconductor parametric test equipment via operation of a parametric test equipment module; and

providing control of the parametric test instrumentation via operation of a test instrumentation module.

43. (Previously Presented) A method of controlling a semiconductor parametric test system, comprising:

controlling via a control module implemented in software and executing on a computerized system, concurrent motion of semiconductor test equipment and operation of parametric test instrumentation;

controlling the state of at least one other system module via a state oscillator module, the state oscillator module controlled by the control module and operable to control the state of other system modules in synchronization with other system events;

providing control of the semiconductor parametric test equipment via operation of a parametric test equipment module, wherein the semiconductor parametric test equipment comprises at least one of a wafer loader, a wafer positioner, a wafer chuck, a wafer tray loader, and a prober; and

providing control of the parametric test instrumentation via operation of a test instrumentation module, wherein the parametric test instrumentation comprises at least one of a test probe and a semiconductor test parameter module.

44-58. (Canceled)